

## **Excellent Integrated System Limited**

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[Diodes Incorporated](#)  
[DMC31D5UDJ-7B](#)

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## Product Summary

Device	$V_{(BR)DSS}$	$R_{DS(ON)}$ max	$I_D$ max $T_A = +25^\circ C$
Q1	30V	1.5Ω @ $V_{GS} = 4.5V$	0.22A
		2.0Ω @ $V_{GS} = 2.5V$	
		3.0Ω @ $V_{GS} = 1.8V$	
		4.5Ω @ $V_{GS} = 1.5V$	
Q2	-30V	5Ω @ $V_{GS} = -4.5V$	-0.2A
		6Ω @ $V_{GS} = -2.5V$	
		7Ω @ $V_{GS} = -1.8V$	
		10Ω @ $V_{GS} = -1.5V$	

## Description

This MOSFET has been designed to minimize the on-state resistance ( $R_{DS(ON)}$ ) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

## Applications

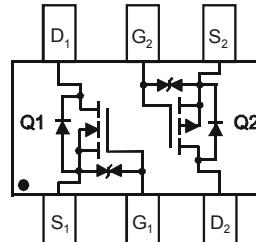
- General Purpose Interfacing Switch
- Power Management Functions
- Analog Switch



Top View



Top View


 Schematic and  
Transistor Diagram

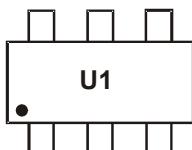
## Ordering Information (Note 4)

Part Number	Case	Packaging
DMC31D5UDJ-7	SOT963	10K/Tape & Reel
DMC31D5UDJ-7B	SOT963	10K/Tape & Reel

Notes:

1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
2. See [http://www.diodes.com/quality/lead\\_free.html](http://www.diodes.com/quality/lead_free.html) for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
4. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>. The options -7 and -7B stand for different taping orientations.

## Marking Information



U1 = Product Type Marking Code



**DMC31D5UDJ**

### Maximum Ratings Q1 N-CHANNEL (@ $T_A = +25^\circ\text{C}$ , unless otherwise specified.)

Characteristic			Symbol	Value	Units
Drain-Source Voltage			$V_{DSS}$	30	V
Gate-Source Voltage			$V_{GSS}$	$\pm 12$	V
Continuous Drain Current (Note 5) $V_{GS} = 4.5\text{V}$	Steady State	$T_A = +25^\circ\text{C}$ $T_A = +70^\circ\text{C}$	$I_D$	220 160	mA
Maximum Continuous Body Diode Forward Current (Note 6)			$I_S$	200	mA
Pulsed Drain Current (Note 6)			$I_{DM}$	600	mA

### Maximum Ratings Q2 P-CHANNEL (@ $T_A = +25^\circ\text{C}$ , unless otherwise specified.)

Characteristic			Symbol	Value	Units
Drain-Source Voltage			$V_{DSS}$	-30	V
Gate-Source Voltage			$V_{GSS}$	$\pm 12$	V
Continuous Drain Current (Note 5) $V_{GS} = -4.5\text{V}$	Steady State	$T_A = +25^\circ\text{C}$ $T_A = +70^\circ\text{C}$	$I_D$	-200 -140	mA
Maximum Continuous Body Diode Forward Current (Note 6)			$I_S$	-200	mA
Pulsed Drain Current (Note 6)			$I_{DM}$	-600	mA

### Thermal Characteristics (@ $T_A = +25^\circ\text{C}$ , unless otherwise specified.)

Characteristic		Symbol	Value	Units
Total Power Dissipation (Note 5)		$P_D$	350	mW
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	$R_{\theta JA}$	361	°C/W
Operating and Storage Temperature Range		$T_J, T_{STG}$	-55 to +150	°C

### Electrical Characteristics Q1 N-CHANNEL (@ $T_A = +25^\circ\text{C}$ , unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
<b>OFF CHARACTERISTICS (Note 7)</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	30	—	—	V	$V_{GS} = 0\text{V}, I_D = 250\mu\text{A}$
Zero Gate Voltage Drain Current @ $T_C = +25^\circ\text{C}$	$I_{DSS}$	—	—	100	nA	$V_{DS} = 24\text{V}, V_{GS} = 0\text{V}$
Gate-Source Leakage	$I_{GSS}$	—	—	$\pm 10$	$\mu\text{A}$	$V_{GS} = \pm 10\text{V}, V_{DS} = 0\text{V}$
<b>ON CHARACTERISTICS (Note 7)</b>						
Gate Threshold Voltage	$V_{GS(th)}$	0.4	—	1.0	V	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$
Static Drain-Source On-Resistance	$R_{DS(ON)}$	—	0.9	1.5	$\Omega$	$V_{GS} = 4.5\text{V}, I_D = 100\text{mA}$
		—	1.0	2.0		$V_{GS} = 2.5\text{V}, I_D = 50\text{mA}$
		—	1.2	3.0		$V_{GS} = 1.8\text{V}, I_D = 20\text{mA}$
		—	1.4	4.5		$V_{GS} = 1.5\text{V}, I_D = 10\text{mA}$
		—	2.3	—		$V_{GS} = 1.2\text{V}, I_D = 1\text{mA}$
		—	—	—		—
Diode Forward Voltage	$V_{SD}$	—	0.6	1.0	V	$V_{GS} = 0\text{V}, I_S = 10\text{mA}$
<b>DYNAMIC CHARACTERISTICS (Note 8)</b>						
Input Capacitance	$C_{iss}$	—	22.6	—	pF	$V_{DS} = 15\text{V}, V_{GS} = 0\text{V}, f = 1.0\text{MHz}$
Output Capacitance	$C_{oss}$	—	2.68	—	pF	
Reverse Transfer Capacitance	$C_{rss}$	—	1.8	—	pF	
Total Gate Charge	$Q_g$	—	0.38	—	nC	$V_{GS} = 4.5\text{V}, V_{DS} = 15\text{V}, I_D = 200\text{mA}$
Gate-Source Charge	$Q_{gs}$	—	0.05	—	nC	
Gate-Drain Charge	$Q_{gd}$	—	0.07	—	nC	
Turn-On Delay Time	$t_{D(on)}$	—	3.2	—	ns	$V_{DD} = 15\text{V}, V_{GS} = 4.5\text{V}, R_G = 2\Omega, I_D = 200\text{mA}$
Turn-On Rise Time	$t_r$	—	2.2	—	ns	
Turn-Off Delay Time	$t_{D(off)}$	—	21	—	ns	
Turn-Off Fall Time	$t_f$	—	7.5	—	ns	



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**Electrical Characteristics Q2 P-CHANNEL (@ $T_A = +25^\circ\text{C}$ , unless otherwise specified.)**

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
<b>OFF CHARACTERISTICS (Note 7)</b>						
Drain-Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	-30	—	—	V	$\text{V}_{\text{GS}} = 0\text{V}$ , $\text{I}_D = -250\mu\text{A}$
Zero Gate Voltage Drain Current @ $T_C = +25^\circ\text{C}$	$\text{I}_{\text{DSS}}$	—	—	100	nA	$\text{V}_{\text{DS}} = -24\text{V}$ , $\text{V}_{\text{GS}} = 0\text{V}$
Gate-Source Leakage	$\text{I}_{\text{GSS}}$	—	—	$\pm 10$	$\mu\text{A}$	$\text{V}_{\text{GS}} = \pm 10\text{V}$ , $\text{V}_{\text{DS}} = 0\text{V}$
<b>ON CHARACTERISTICS (Note 7)</b>						
Gate Threshold Voltage	$\text{V}_{\text{GS(th)}}$	-0.4	—	-1.0	V	$\text{V}_{\text{DS}} = \text{V}_{\text{GS}}$ , $\text{I}_D = -250\mu\text{A}$
Static Drain-Source On-Resistance	$\text{R}_{\text{DS(ON)}}$	—	2.0	5	$\Omega$	$\text{V}_{\text{GS}} = -4.5\text{V}$ , $\text{I}_D = -100\text{mA}$
		—	2.5	6		$\text{V}_{\text{GS}} = -2.5\text{V}$ , $\text{I}_D = -50\text{mA}$
		—	3.0	7		$\text{V}_{\text{GS}} = -1.8\text{V}$ , $\text{I}_D = -20\text{mA}$
		—	3.4	10		$\text{V}_{\text{GS}} = -1.5\text{V}$ , $\text{I}_D = -10\text{mA}$
		—	5.1	—		$\text{V}_{\text{GS}} = -1.2\text{V}$ , $\text{I}_D = -1\text{mA}$
Diode Forward Voltage	$\text{V}_{\text{SD}}$	—	-0.6	-1.0	V	$\text{V}_{\text{GS}} = 0\text{V}$ , $\text{I}_S = -10\text{mA}$
<b>DYNAMIC CHARACTERISTICS (Note 8)</b>						
Input Capacitance	$\text{C}_{\text{iss}}$	—	21.8	—	pF	$\text{V}_{\text{DS}} = -15\text{V}$ , $\text{V}_{\text{GS}} = 0\text{V}$ , $f = 1.0\text{MHz}$
Output Capacitance	$\text{C}_{\text{oss}}$	—	2.82	—	pF	
Reverse Transfer Capacitance	$\text{C}_{\text{rss}}$	—	1.66	—	pF	
Total Gate Charge	$\text{Q}_g$	—	0.35	—	nC	
Gate-Source Charge	$\text{Q}_{\text{gs}}$	—	0.05	—	nC	
Gate-Drain Charge	$\text{Q}_{\text{gd}}$	—	0.10	—	nC	$\text{V}_{\text{GS}} = -4.5\text{V}$ , $\text{V}_{\text{DS}} = -15\text{V}$ , $\text{I}_D = -200\text{mA}$
Turn-On Delay Time	$\text{t}_{\text{D(on)}}$	—	3.5	—	ns	
Turn-On Rise Time	$\text{t}_r$	—	5.2	—	ns	
Turn-Off Delay Time	$\text{t}_{\text{D(off)}}$	—	18.8	—	ns	
Turn-Off Fall Time	$\text{t}_f$	—	8.7	—	ns	

Notes:

5. Device mounted on FR-4 PCB, with minimum recommended pad layout.
6. Device mounted on minimum recommended pad layout test board, 10 $\mu\text{s}$  pulse duty cycle = 1%.
7. Short duration pulse test used to minimize self-heating effect.
8. Guaranteed by design. Not subject to product testing.



**DMC31D5UDJ**

**N-CHANNEL**

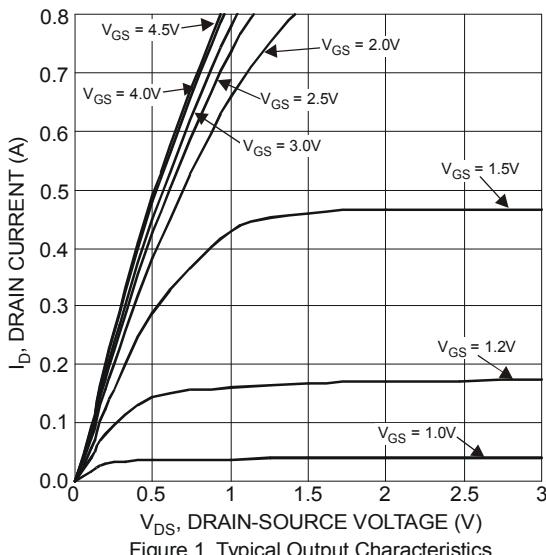


Figure 1 Typical Output Characteristics

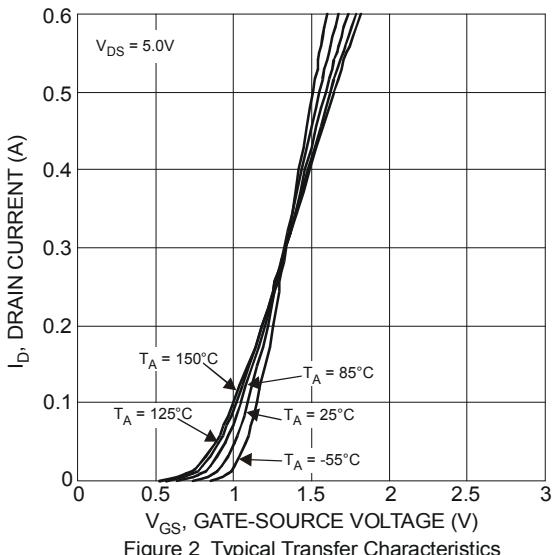


Figure 2 Typical Transfer Characteristics

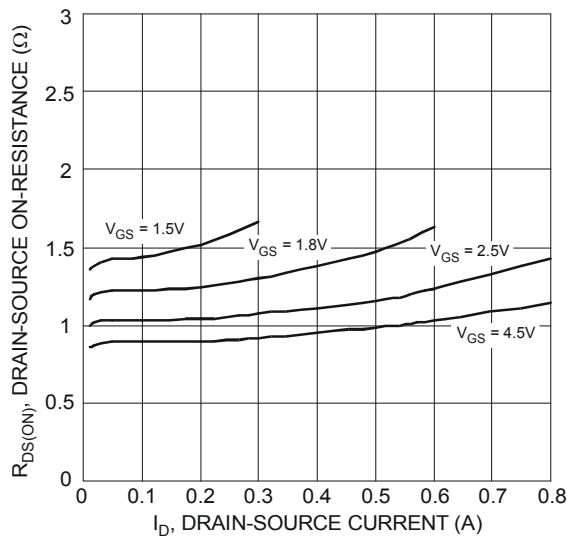


Figure 3 Typical On-Resistance vs.  
Drain Current and Gate Voltage

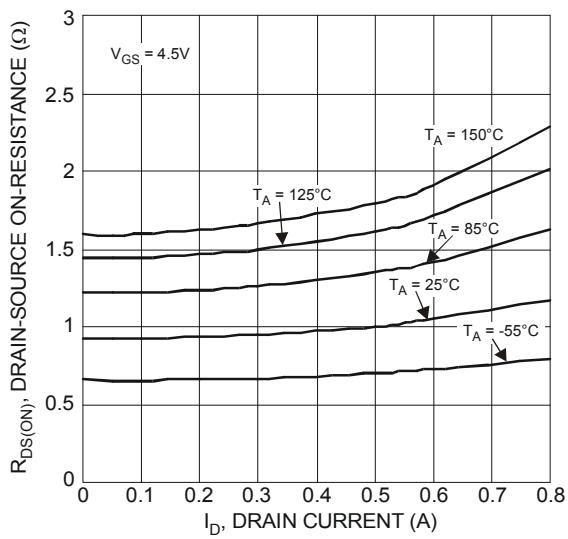


Figure 4 Typical On-Resistance vs.  
Drain Current and Temperature

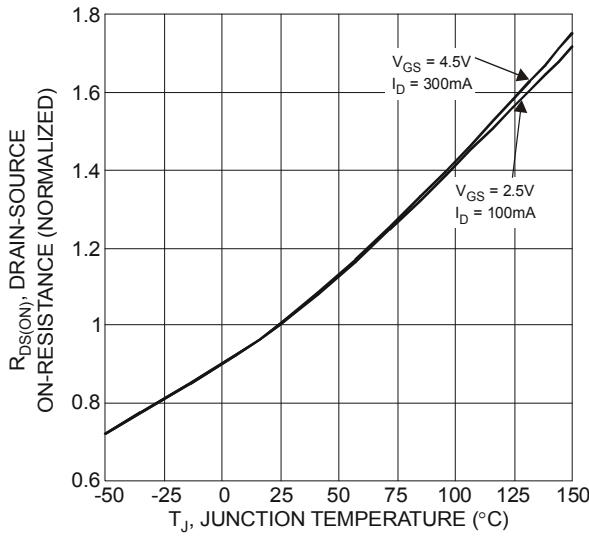


Figure 5 On-Resistance Variation with Temperature

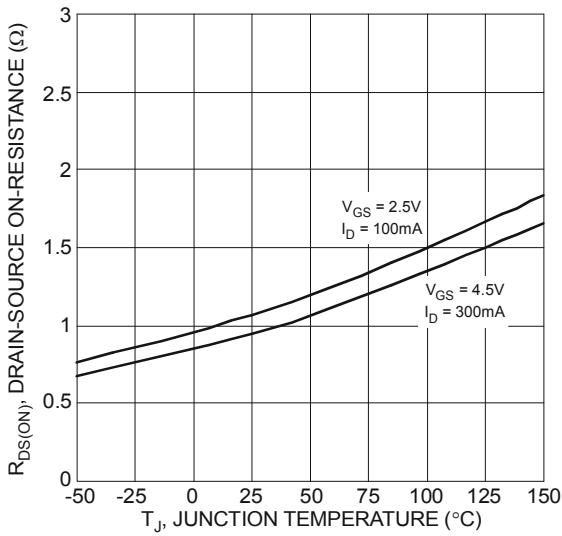


Figure 6 On-Resistance Variation with Temperature



**DMC31D5UDJ**

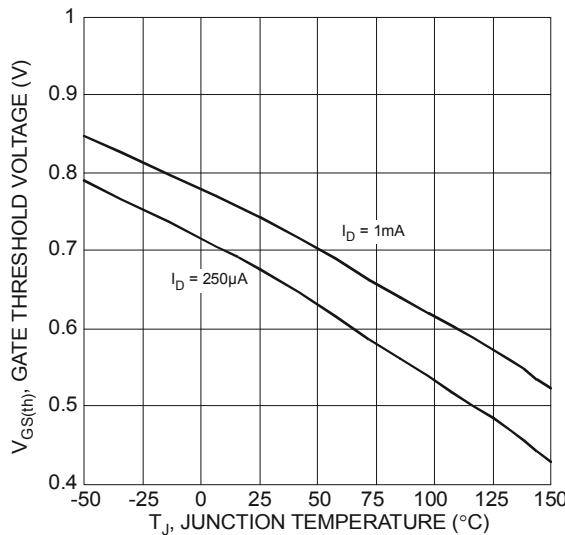


Figure 7 Gate Threshold Variation vs. Ambient Temperature

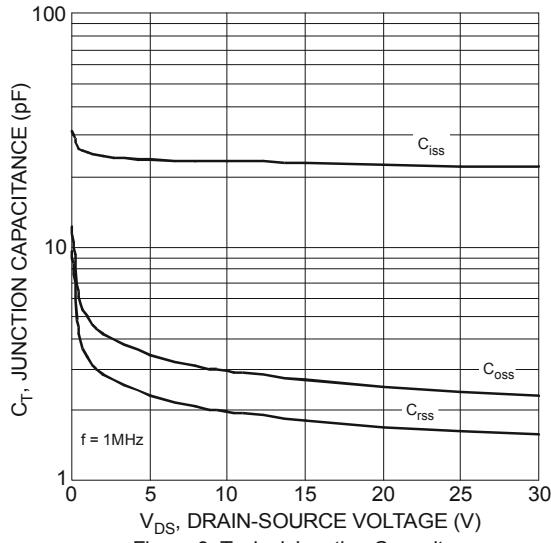


Figure 9 Typical Junction Capacitance

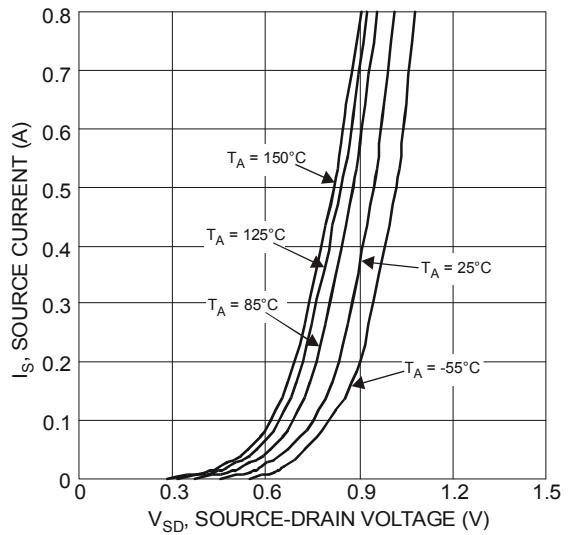


Figure 8 Diode Forward Voltage vs. Current

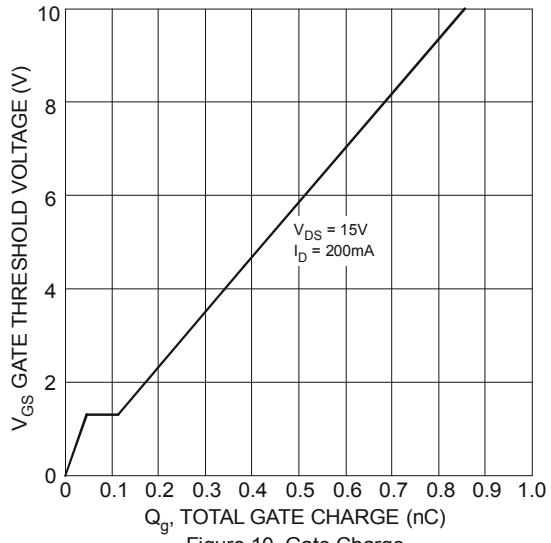


Figure 10 Gate Charge

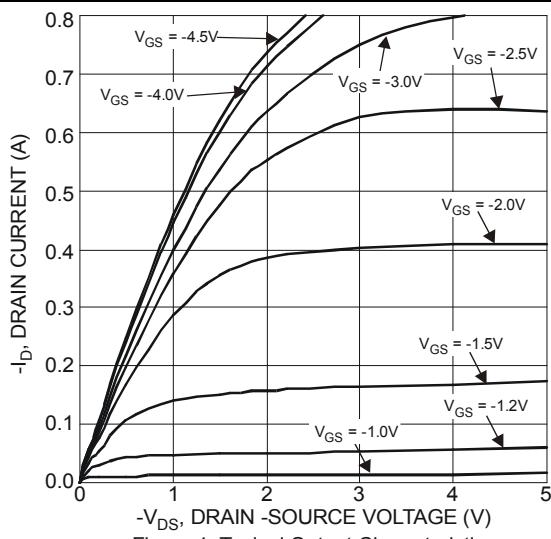


Figure 1 Typical Output Characteristics

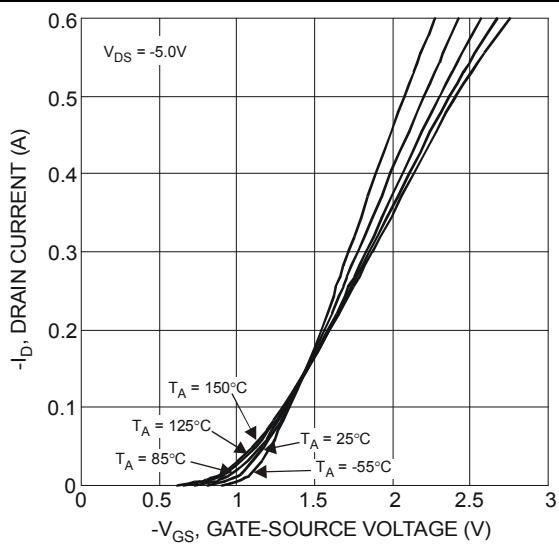


Figure 2 Typical Transfer Characteristics

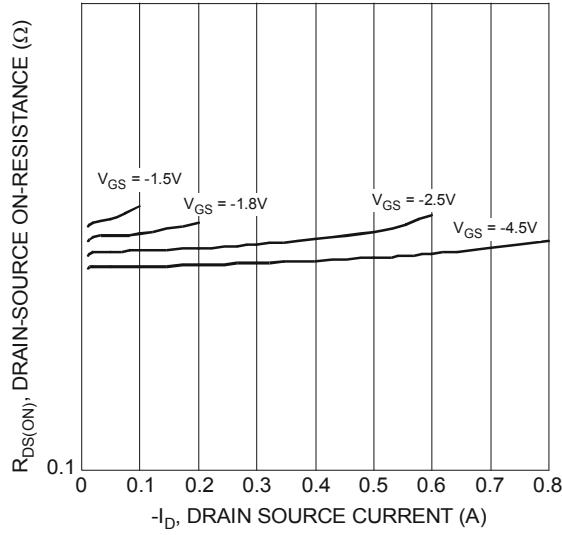


Figure 3 Typical On-Resistance vs.  
Drain Current and Gate Voltage

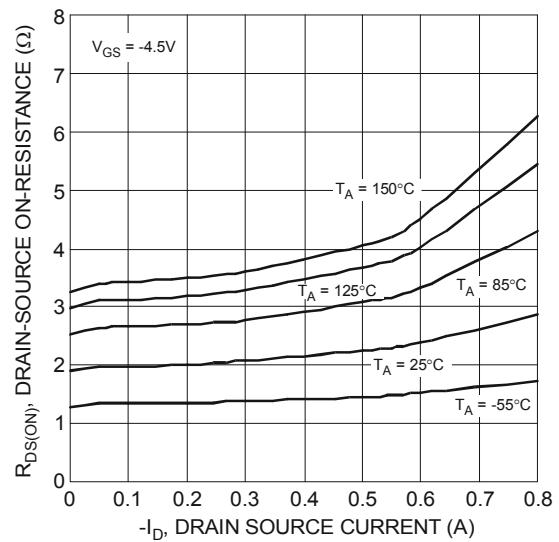


Figure 4 Typical On-Resistance vs.  
Drain Current and Temperature

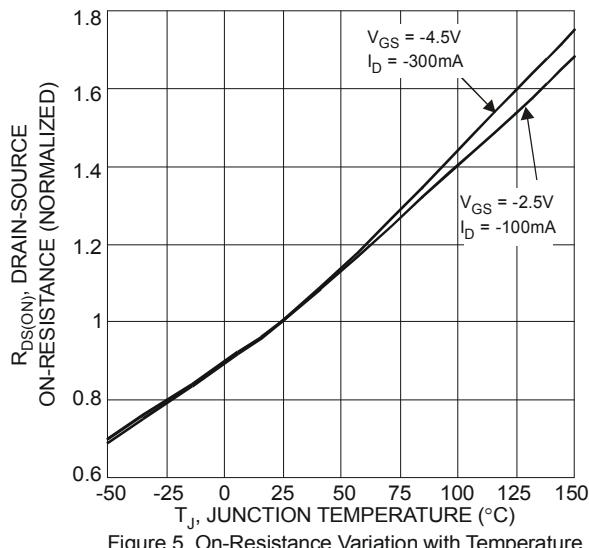


Figure 5 On-Resistance Variation with Temperature

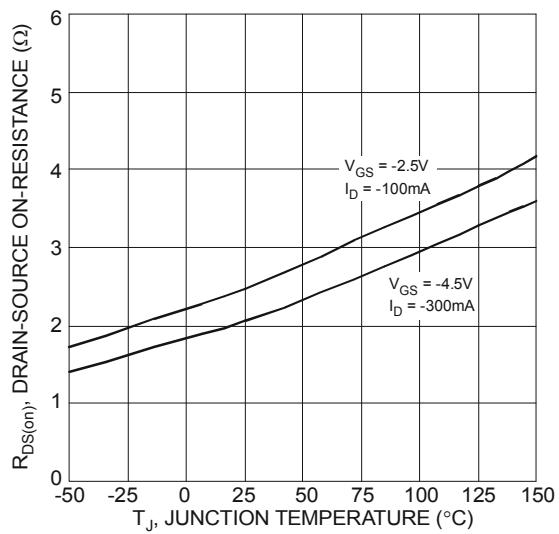


Figure 6 On-Resistance Variation with Temperature



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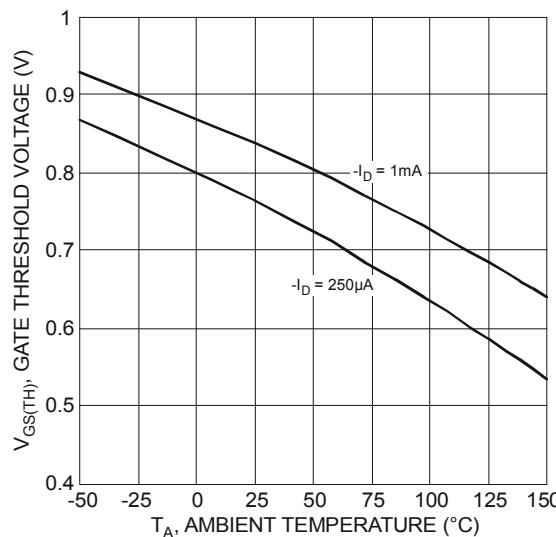


Figure 7 Gate Threshold Variation vs. Ambient Temperature

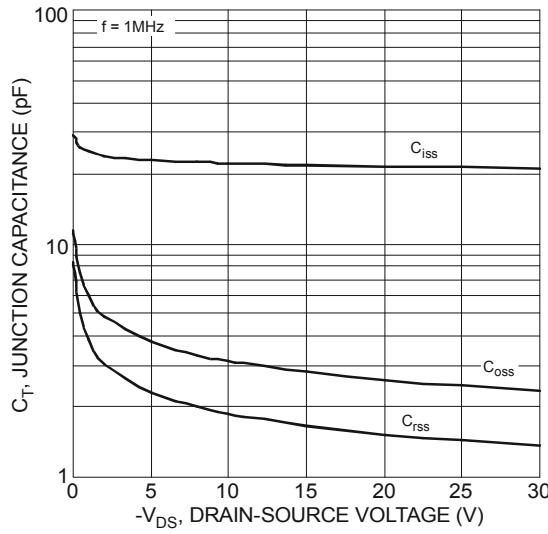


Figure 9 Typical Junction Capacitance

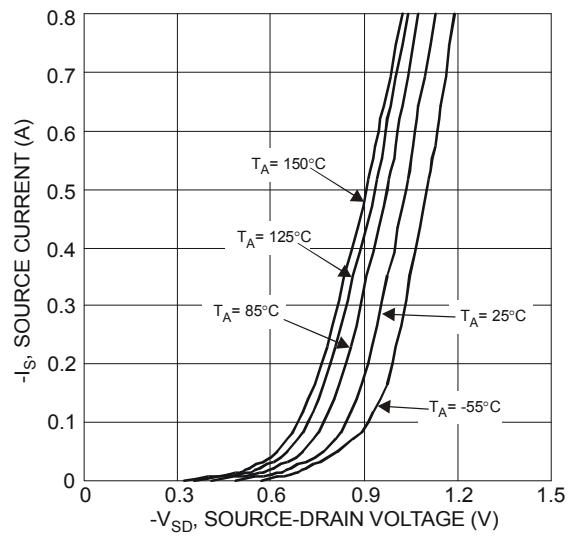


Figure 8 Diode Forward Voltage vs. Current

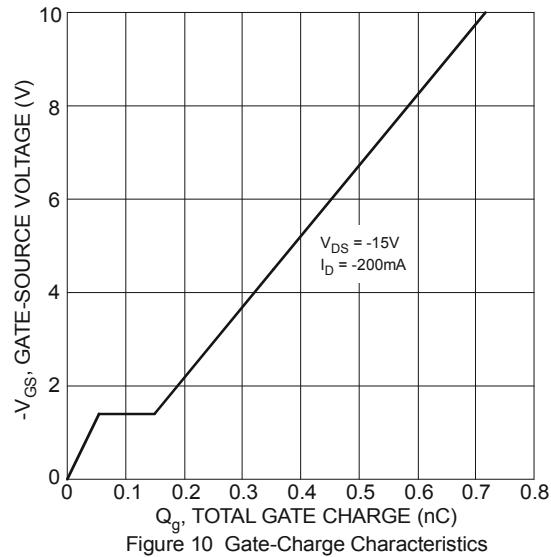


Figure 10 Gate-Charge Characteristics

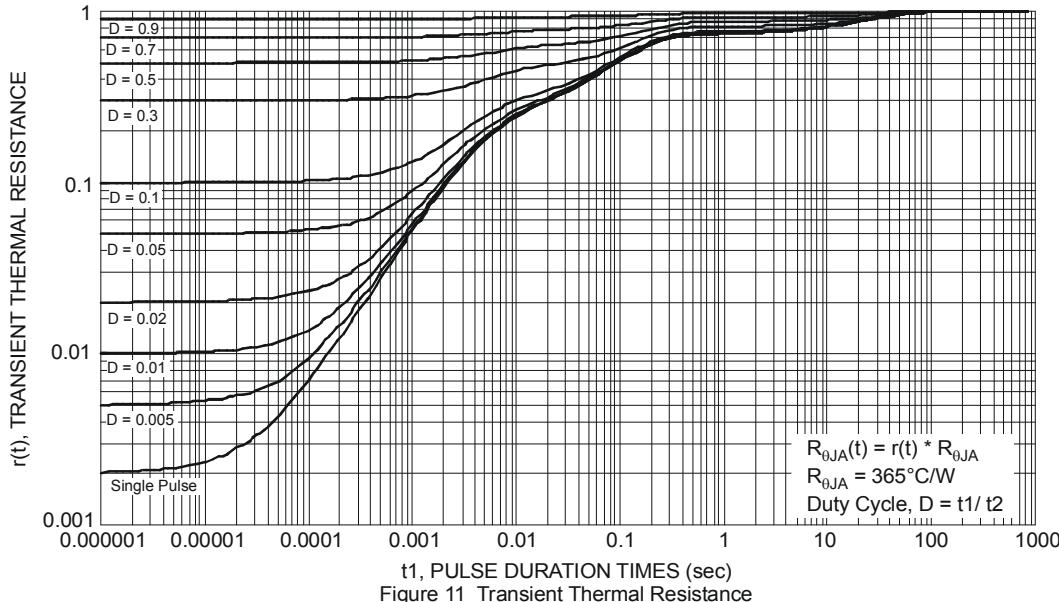


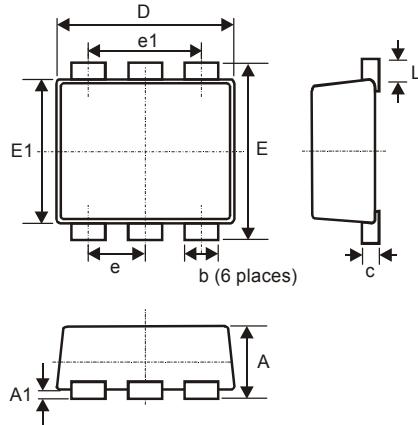
Figure 11 Transient Thermal Resistance



**DMC31D5UDJ**

## Package Outline Dimensions

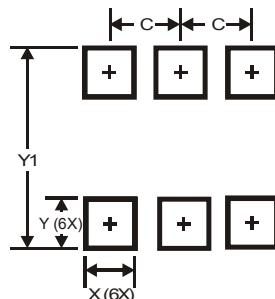
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for the latest version.



SOT963			
Dim	Min	Max	Typ
<b>A</b>	0.40	0.50	0.45
<b>A1</b>	0	0.05	-
<b>c</b>	0.120	0.180	0.150
<b>D</b>	0.95	1.05	1.00
<b>E</b>	0.95	1.05	1.00
<b>E1</b>	0.75	0.85	0.80
<b>L</b>	0.05	0.15	0.10
<b>b</b>	0.10	0.20	0.15
<b>e</b>	0.35 Typ		
<b>e1</b>	0.70 Typ		
All Dimensions in mm			

## Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



Dimensions	Value (in mm)
<b>C</b>	0.350
<b>X</b>	0.200
<b>Y</b>	0.200
<b>Y1</b>	1.100

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